

DATA SHEET

● DEVICE NUMBER : BWL-10C1W06-S

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2009.12.29	1.0	1.0	1.0	1.0	1.0	1.0					Preliminary

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BRIGHT LED ELECTRONICS CORP.



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APPROVED	DRAWER
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● Features:

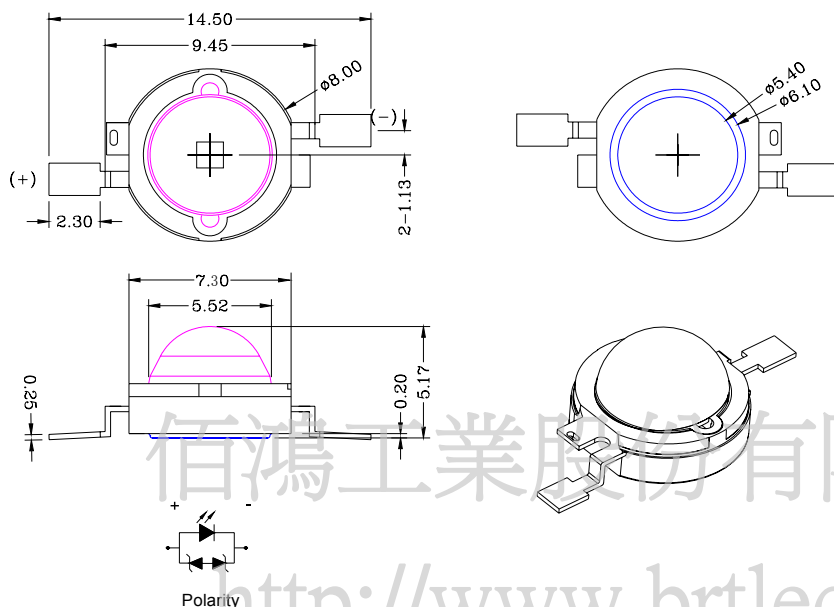
1. Input power: 1W.
 2. Chip material: InGaN.
 3. Emitted color: Warm white.
 4. High lumen output.
 5. High flux density.
 6. Low power consumption.
 7. Efficient heat transfer.
 8. Exterior lens is silicon.
 9. Add extra heat sink is necessary.
- * Must increasing heatsink, let the unit temperature below 60 °C.



● Applications:

1. Torch.
2. Head Light.
3. Architectural Lighting.
4. LCD Backlight.

● Package dimensions :



Notes:

1. All dimensions are in millimeters.
2. Tolerance is $\pm 0.5\text{mm}$ unless otherwise specified.

● Absolute maximum ratings ($T_J=25^{\circ}\text{C}$)

Parameter	Symbol	Rating	Unit
Power Dissipation	P_D	1.0	W
DC Forward Current ^{*1}	I_F	350	mA
Peak Pulsed Forward Current ^{*2}	I_{FP}	1.0	A
LED Junction Temperature	T_J	130	$^{\circ}\text{C}$
Operating Temperature	T_{opr}	-30~120	$^{\circ}\text{C}$
Storage Temperature	T_{stg}	-40~120	$^{\circ}\text{C}$
Reverse Voltage	V_R	5	V
Soldering Temperature (T=5 sec)	T_{sol}	300 ± 5	$^{\circ}\text{C}$

^{*1}Proper current derating must be followed to keep LED junction temperature (T_J) below the maximum.

^{*2}Condition for I_{FP} is pulsed with 1/10 duty and 0.1msec width.

● Electrical & Optical Characteristics ($T_J=25^{\circ}\text{C}$)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F = 350\text{mA}$	-	3.5	4.0	V
Total Flux	Φ_v	$I_F = 350\text{mA}$	60	65	-	lm
Color Temperature	CCT	$I_F = 350\text{mA}$	2580	-	3710	K
Reverse Current	I_R	$V_R=5\text{V}$	-	-	10	μA
Thermal Resistance, Junction To Case	$R_{\theta J-C}$	$I_F = 350\text{mA}$	-	9	-	$^{\circ}\text{C}/\text{W}$
Viewing Angle	$2\theta_{1/2}$	$I_F = 350\text{mA}$	-	120	-	degree

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Typical electro-optical characteristics curves

Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

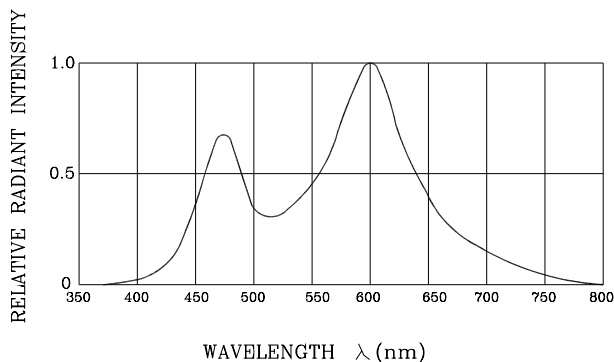


Fig.2 FORWARD CURRENT VS. AMBIENT TEMPERATURE

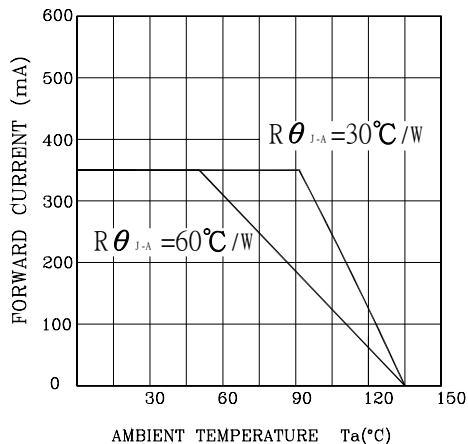


Fig.3 FORWARD CURRENT VS. FORWARD VOLTAGE

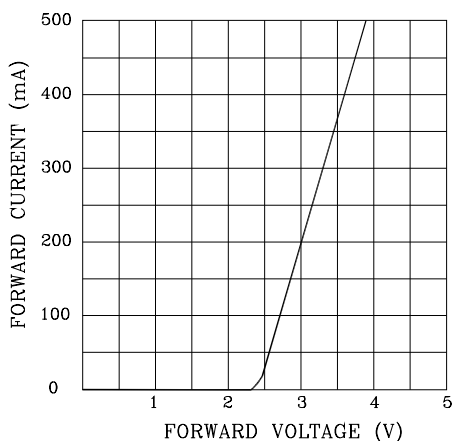


Fig.4 RELATIVE LUMINOUS INTENSITY VS. JUNCTION TEMPERATURE

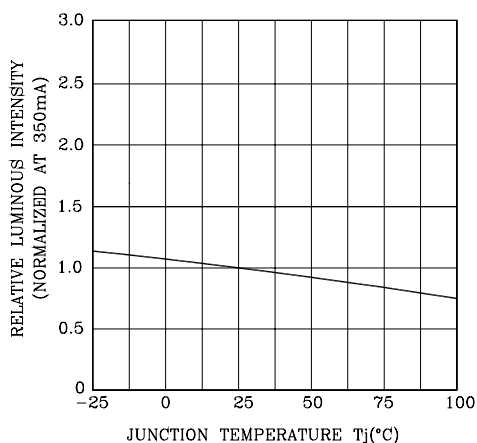


Fig.5 RELATIVE LUMINOUS INTENSITY VS. FORWARD CURRENT

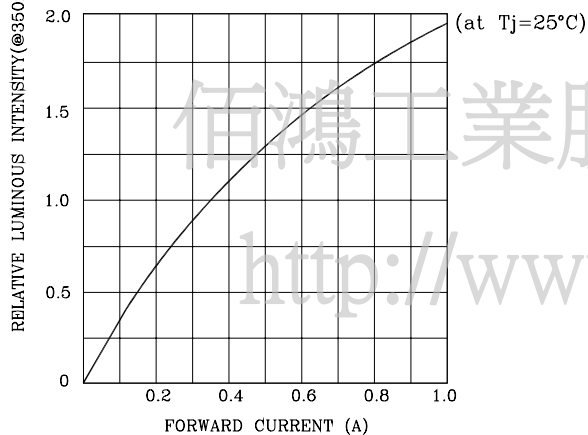
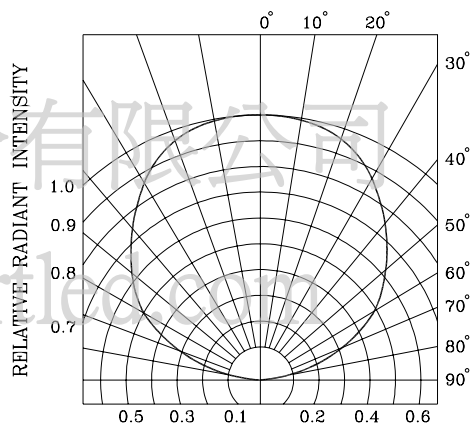
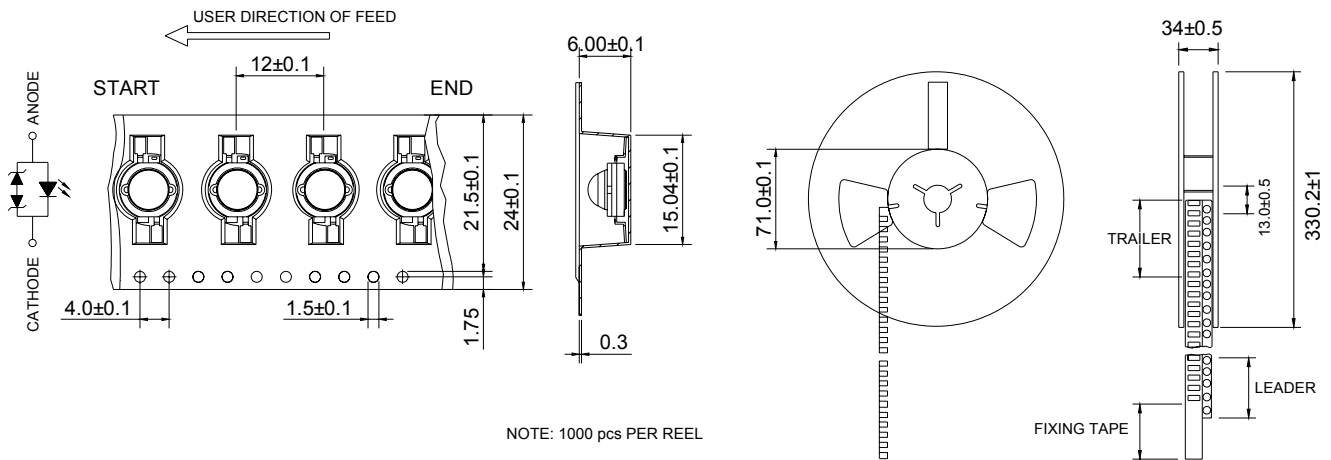


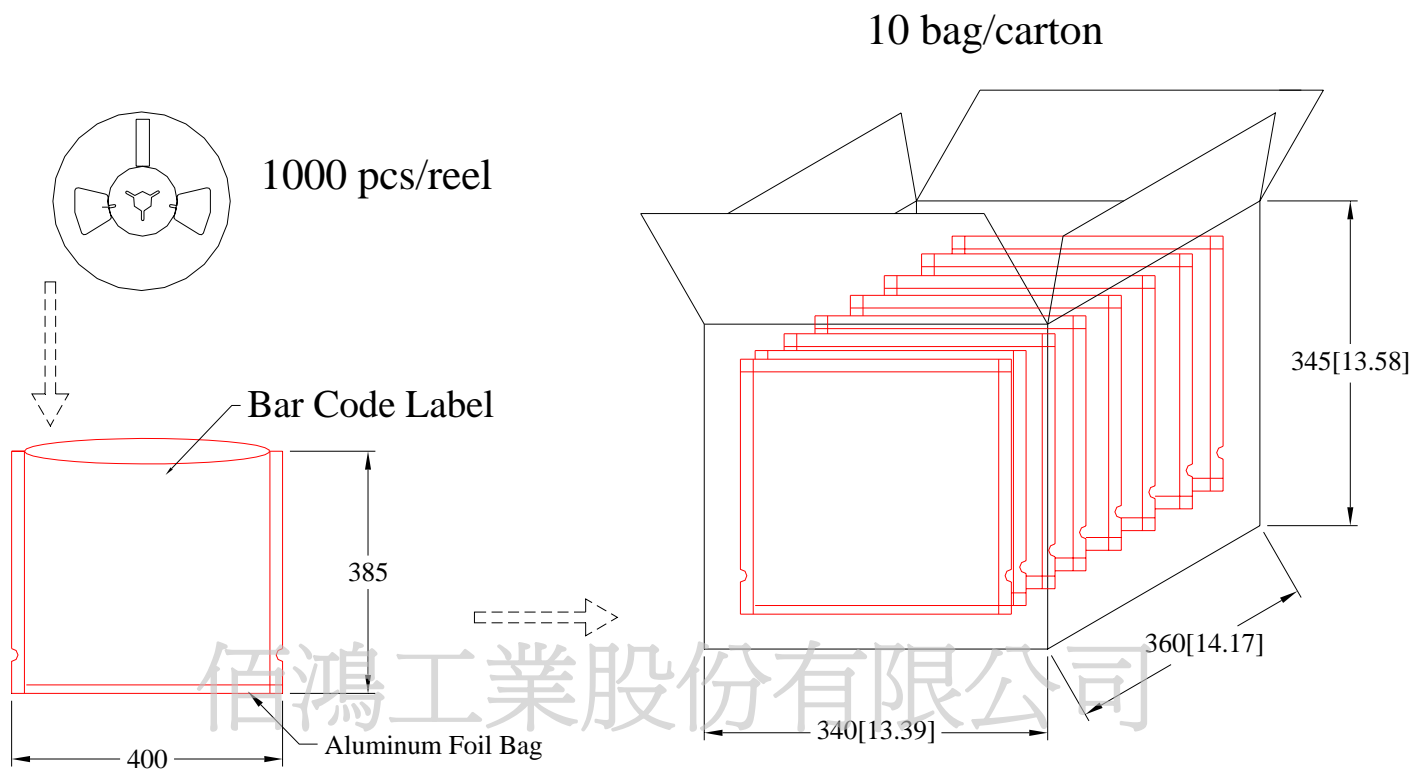
Fig.6 RADIATION DIAGRAM



● Tapping and packaging specifications(Units: mm)



● Package Method : (unit:mm)



NOTES : Bag : Tolerance is ± 5 mm unless otherwise noted.

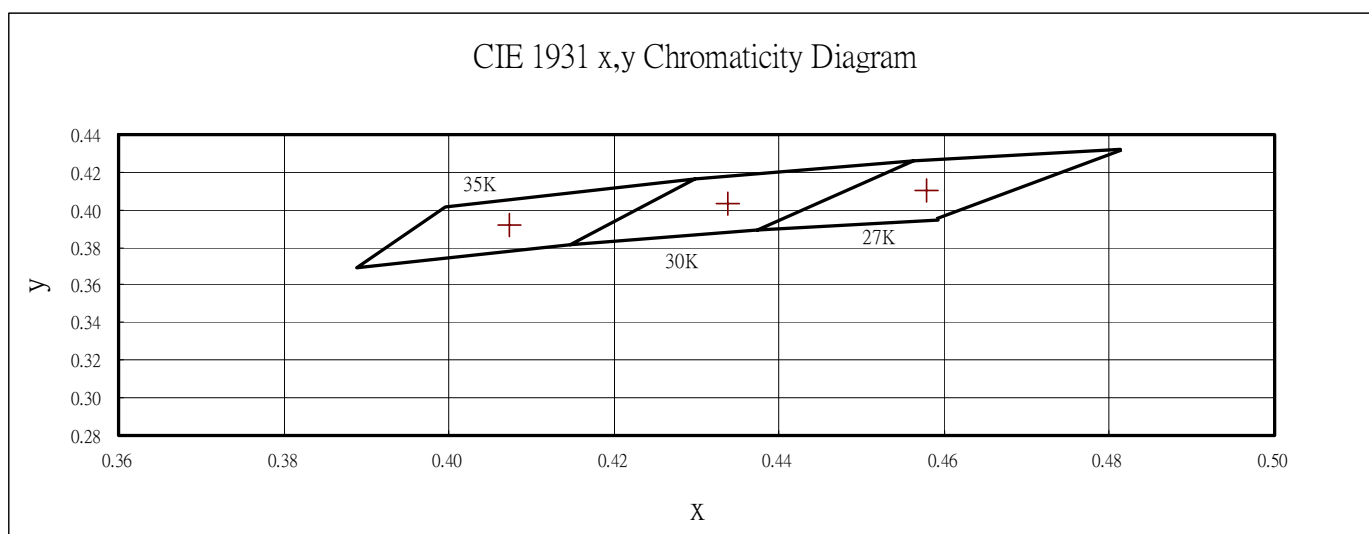
Carton : Tolerance is ± 10 mm unless otherwise noted.

● Total Flux Bin Limits (At 350mA)

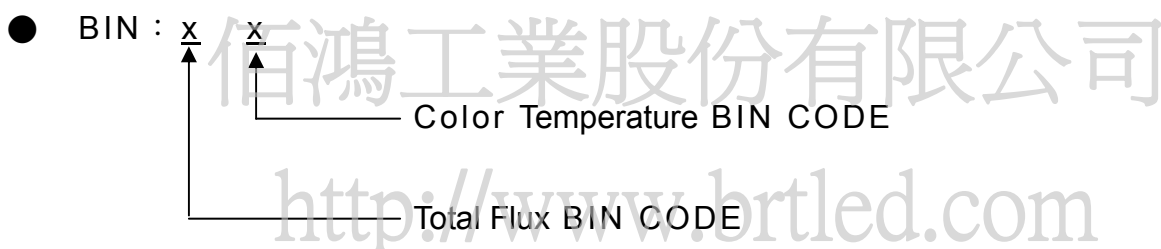
BIN CODE	Min. (lm)	Max. (lm)
N	60	72
P	72	93

Tolerance for each Bin limit is $\pm 15\%$

● Color Temperature Bin Limits(At 350mA)



BIN CODE	Nominal CCT	CCT Range	Chromaticity Coordinates			
K27	2700K	2580-2870	x	0.4578	0.4813	0.4562
			y	0.4101	0.4319	0.4260
K30	3000K	2870-3220	x	0.4338	0.4562	0.4299
			y	0.4030	0.4260	0.4165
K35	3500K	3220-3710	x	0.4073	0.4299	0.3996
			y	0.3917	0.4165	0.4015



Notes:

1. Bin categories are established for classification of products.

Products may not be available in all bin categories.

● Notes for designing:

Current limiting resistor or a constant current power supply must be used in the circuit to drive BRIGHT LEDs within the rated figures and not to overload BRIGHT LEDs with instantaneous voltage at the turning ON and OFF cycles.

When using pulse driving, the average current must be within the rated figures. And the circuit should be designed to avoid reverse voltage when turning off the BRIGHT LEDs.

● Storage:

In order to avoid the absorption of moisture, it is recommended to solder BRIGHT LEDs as soon as possible after unpacking the sealed envelope.

If the envelope is still packed, to store it in the environment as following:

- (1) Temperature : 5°C-30°C (41°F) Humidity : RH 60% Max.
- (2) After this bag is opened, devices that will be applied to infrared reflow, vapor-phase reflow, or equivalent soldering process must be:
 - a. Completed within 168 hours.
 - b. Stored at less than 30% RH.
- (3) Devices require baking before mounting, if:
 - (2) a or (2) b is not met.
- (4) If baking is required, devices must be baked under below conditions:
 - 48 hours at 60°C±3°C.

● Package and Label of Products:

- (1) Package: Products are packed in one bag of 1000 pcs (one taping reel) and a label is attached to each bag.
- (2) Label:

